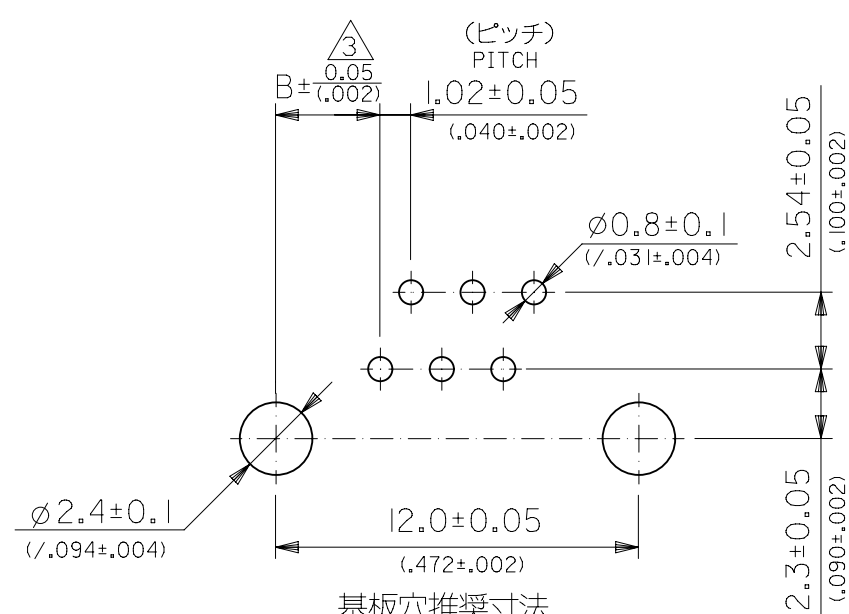


- 注) NOTES
- 材質 MATERIAL
ハウジング: ガラス入りポリエステル UL94V-0
HSG.: POLYESTER G.F.15% UL94V-0
ターミナル: リン青銅
TERM.: PHOSPHOR BRONZE
 - メッキ仕様 PLATING
接点部: 金メッキ、表参照
CONTACT AREA: GOLD PER TABLE
半田付け部: 錫メッキ 1.0µmMIN.
SOLDER AREA: TIN 1.0 MICROMETER MINIMUM.
下地メッキ: ニッケルメッキ 1.0µmMIN.
UNDERPLATE: NICKEL 1.0 MICROMETER MINIMUM.
 - △ 64*6は両端の基板穴を除く。
62*6は両端の2つの基板穴を除く。
DIM B INDICATES FIRST P.C.HOLE REQUIRED PER PART NUMBER.
FOR PARTIALLY LOADED ASSEMBLIES P.C.HOLE PATTERN IS REDUCED FROM EACH END.
 - 推奨基板厚: t=1.6±0.05
RECOMMENDED P.C.B. THICKNESS: 1.6±0.05
 - △ 金メッキ厚標示
COLOR CODING TO INDICATE GOLD PLATING
黄色: 0.1µmMIN. YELLOW: 0.1 MICROMETER MINIMUM.
緑色: 0.38µmMIN. GREEN: 0.38 MICROMETER MINIMUM.
オレンジ色: 0.76µmMIN. ORANGE: 0.76 MICROMETER MINIMUM.
無色: 1.27µmMIN. UNMARKED: 1.27 MICROMETER MINIMUM.
 - ハウジングの色は、グレイ。
HOUSING COLOR IS GRAY.
 - 本製品は52018-6**5の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52018-6**5.



基板穴推奨寸法
RECOMMENDED P.C.B. LAYOUT
(ジャック取付け側)
(JACK ASS'Y SIDE)

MATERIAL 材料	注参照 SEE NOTES
FINISH 仕上げ	注及び表参照 SEE NOTES AND CHART
WIRE RANGE 適用電線範囲	— # —
INS. RANGE 被覆外径	— # —

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差																					
10 UNDER 未満	±0.2	<table border="1"> <tr> <th>DIMENSION UNITS</th> <th>SCALE</th> </tr> <tr> <td>MM</td> <td>4:1</td> </tr> <tr> <td colspan="2">GENERAL TOLERANCES (UNLESS SPECIFIED)</td> </tr> <tr> <td>4 PLACES</td> <td>±</td> </tr> <tr> <td>3 PLACES</td> <td>±</td> </tr> <tr> <td>2 PLACES</td> <td>±</td> </tr> <tr> <td>1 PLACE</td> <td>±</td> </tr> <tr> <td>0 PLACES</td> <td>±</td> </tr> <tr> <td colspan="2">ANGULAR TOL</td> <td>± °</td> </tr> </table>	DIMENSION UNITS	SCALE	MM	4:1	GENERAL TOLERANCES (UNLESS SPECIFIED)		4 PLACES	±	3 PLACES	±	2 PLACES	±	1 PLACE	±	0 PLACES	±	ANGULAR TOL		± °
DIMENSION UNITS	SCALE																				
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1 PLACE	±																				
0 PLACES	±																				
ANGULAR TOL		± °																			
10 OVER 以上	±0.25																				
30 OVER 以上	±0.3																				
ANGLE 角度	±3°																				

6	6	5.08 (.200)	3.46 (.136)	1.27 / (50)	52018-6646
POSITION	極数 CIRCUITS	A	B	金メッキ厚 µm/(µMIN) GOLD PLATING THK(MIN.) µm/(µMIN)	製品番号 MATERIAL No.
MODEL NO.		52018-6**6			

PENDING APPROVAL

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									
CURRENT REV DESC:									
EC NO: 628958		MODULAR JACK HOUSING ASSY -LEAD FREE-							
DRWN: AKUMAR19		PRODUCT CUSTOMER DRAWING							
CHK'D:		2018/08/22		DOCUMENT NUMBER		DOC TYPE		REVISION	
APPR:		INITIAL REVISION:		SD-52018-003		PSD		001 A	
DRWN: M.NAGATA		2004/05/14		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
APPR: M.SASAO		2004/05/14		SEE TABLE		GENERAL MARKET		1 OF 1	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION		DRAWING		SERIES		52018	
		B-SIZE							

DOCUMENT STATUS	RQ	RELEASE DATE
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